



HS REVIEW SUB-COMMITTEE
WORKING GROUP

-
1st Session
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NR0336E1
(+ Annex)
O. Eng.

Brussels, 25 November 2002.

NEW NOTE 4 TO CHAPTER 85 AND EXPLANATORY NOTES TO HEADING 85.23

(PROPOSAL BY THE ICC)

(Item II.3 on Agenda)

Reference documents :

NR0229E1 (RSC/25)	NR0332E2, Annexes C/14 and F/9 (RSC/26 – Report)
NR0285E1 (RSC/26)	NR0332E2, Annexes C/15 and F/5 (RSC/26 – Report)
NR0286E1 (RSC/26)	NR0332E2, Annex C/16 (RSC/26 – Report)
NR0287E1 (RSC/26)	NR0332E2, Annexes C/17 and F/10 (RSC/26 – Report)
NR0288E1 (RSC/26)	NR0332E2, Annexes C/18 and F/11 (RSC/26 – Report)
NR0289E1 (RSC/26)	NR0332E2, Annexes D/2 and F/15 (RSC/26 – Report)
NR0315E1 (RSC/26)	NR0332E2, Annex D/5 (RSC/26 – Report)
NR0319E1 (RSC/26)	NR0332E2, Annexes D/7 and F/20 (RSC/26 – Report)
NR0320E1 (RSC/26)	NR0332E2, Annexes D/8 and F/21 (RSC/26 – Report)
NR0323E1 (RSC/26)	NR0332B2, Annex F/4 (RSC/26 – Report)
NR0325E1 (RSC/26)	NR0332B2, Annex F/19 (RSC/26 – Report)
NR0326E1 (RSC/26)	NR0334E1 (RSC/WG/1)
NR0333B1 (RSC/26)	NR0335E1 (RSC/WG/1)

I. BACKGROUND

1. Following the discussions in the HS Review Sub-Committee (26th Session – September 2002) on the possible amendments to Chapters 84 and 85 concerning information technology products, the Secretariat received a note from the ICC containing a proposal to amend the Nomenclature and the Explanatory Notes with a view to clarifying the classification of “flash memory cards” and “flash electronic storage cards”. This note is reproduced in the Annex to this document.

File No. 2818
File No. 2804

II. SECRETARIAT COMMENTS

2. The Secretariat has also reproduced the Note proposed by ICC in the Annex to Doc. NR0334E1, which document sets out the Secretariat's synthesis of all relevant proposals. It has, however, not reproduced the proposed amendment to the Explanatory Note to heading 85.23 in that document, pending the outcome of the discussions in the Working Group, on the new structure of Chapter 85.
3. Finally, the Secretariat would like to draw the Working Group's attention to Doc. NR0332B2, Annexes D/2 and F/15 (RSC/26 – Report), which set out the proposal prepared by the Secretariat on this issue.

III. CONCLUSION

4. The Working Group is invited to take the text proposed by the ICC into account, when it examines Agenda Item II.1.

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Proposal by the ICC

New Note 4 to Chapter 85

“4.- For the purposes of headings 85.23 and 85.24, “solid-state, non-volatile data storage devices (“flash memory cards” or “flash electronic storage cards”)” are devices comprised of, in the same housing, one or more non-volatile semiconductor memories (for example, “FLASH E²PROM”) in the form of integrated circuits mounted on a printed circuit board (“PCB”) or in a multi-chip integrated circuit (“IC”) package; whether or not including a microcontroller in the form of an integrated circuit; including discrete, passive components; and with a connective capability to a host appliance.”

Explanatory Note to heading 85.23

New second and third paragraphs

Insert the following new second and third paragraphs :

“This heading also includes solid-state, non-volatile data storage devices (known as “flash memory cards” or “flash electronic storage cards”) (see Note 4 to this Chapter). Flash memory cards are usually presented in one of the following formats :

- (1) Devices consisting of an assembly (i) containing a PCB onto which are mounted (a) one or more non-volatile semiconductor memories (for example, FLASH E²PROM) in the form of integrated circuits, (b) with or without a microcontroller in the form of an integrated circuit, (c) with or without passive elements such as capacitors and resistors; and (ii) optionally top and bottom lidded using plastics, metal, or similar material; and (iii) having a connective capability to the host appliance through physical or electromagnetic means. The various assembly components are typically mounted by surface mount technology or by gluing onto the PCB. The PCB is not produced by thin- or thick film technology.
- (2) Devices consisting of an assembly (i) containing a multi-chip IC package that consists of (a) one or more non-volatile semiconductor memories (for example, FLASH E²PROM) in the form of integrated circuits, (b) with or without a microcontroller in the form of an integrated circuit, (c) with passive elements such as capacitors and resistors, and (d) with such components mounted on a metal lead frame or a PCB; (ii) with such assembly then (a) encapsulated by plastic or similar material and (b) optionally top and bottom lidded using plastics, metal, or similar material; and (iii) with such assembly having a connective capability to the host appliance through physical or electromagnetic means. The multi-chip IC package or PCB is not produced by thin- or thick-film technology.

Flash memory cards are used for the storage and retrieval of digital data by an external source. The external source may include, but is not limited to host appliances such as navigation and global positioning systems; data collection terminals; portable scanners; medical monitoring appliances; home appliances; audio and video recording, playback and imaging apparatus; personal communicators (“pagers”); mobile phones and “smartphones”; personal digital assistants (PDAs); personal computers and other automatic data processing

machines and their peripherals; digital networking devices; and digital cameras. This data can be stored onto and read from the card once it has been connected to that particular appliance; such connectivity may or may not require an adapter. Any microcontrollers may be programmed. The cards only use power supplied from the appliances to which they are connected, and require no battery.”
